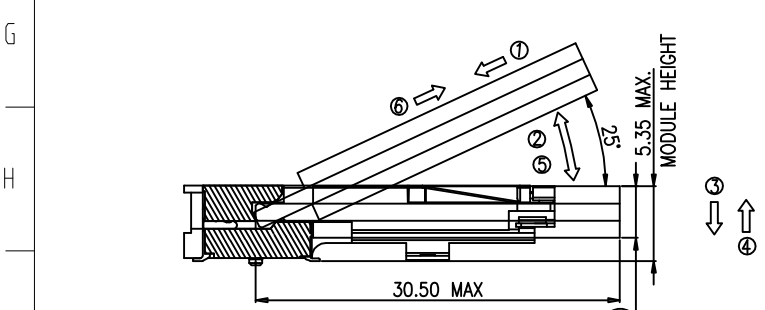
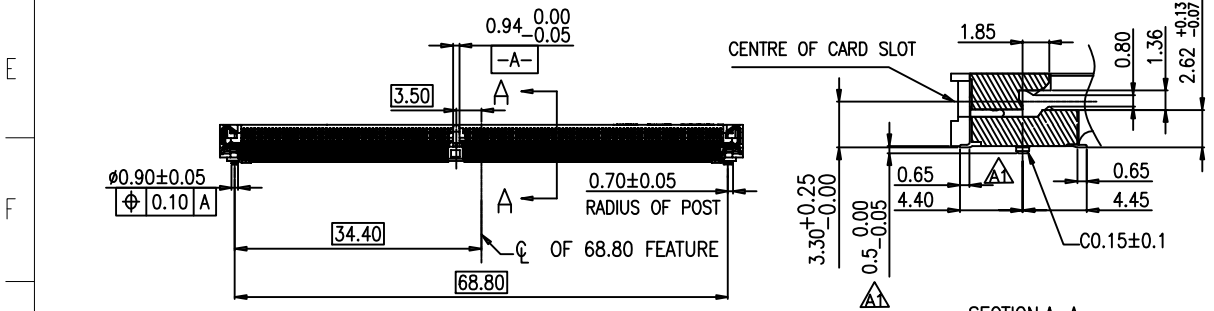
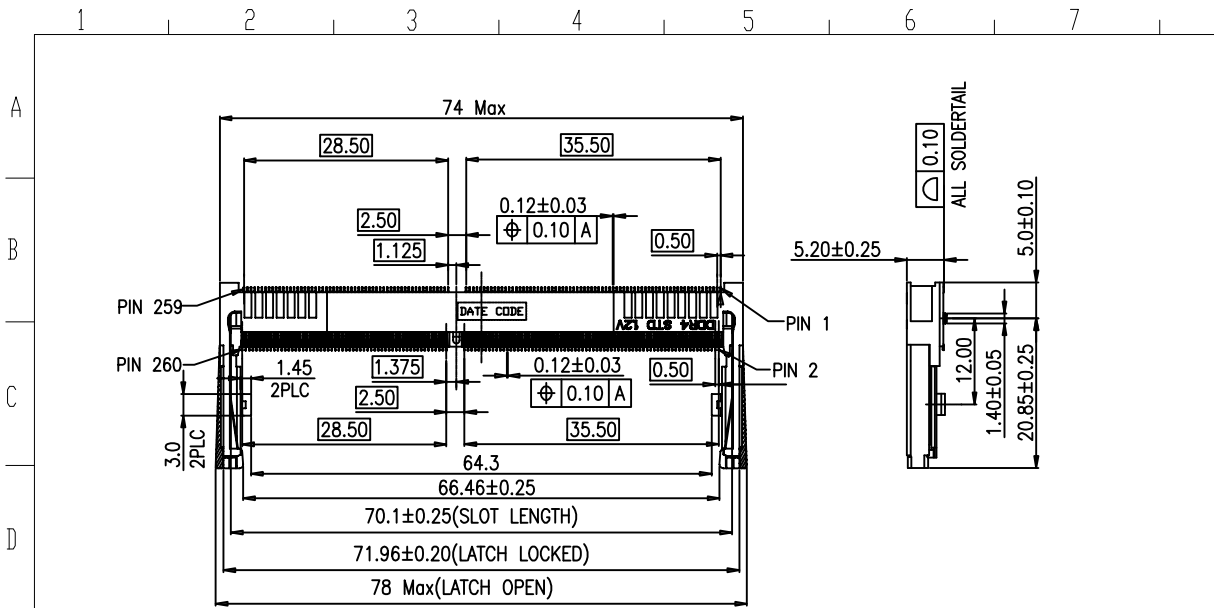


更改 REV	變更內容 MODIFICATION
A	EC06685
B	EC06954



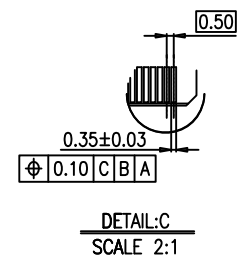
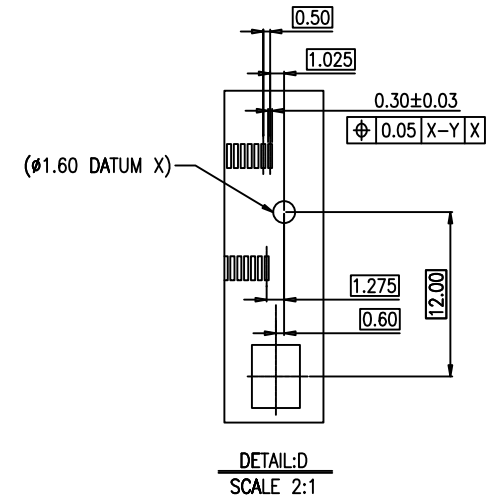
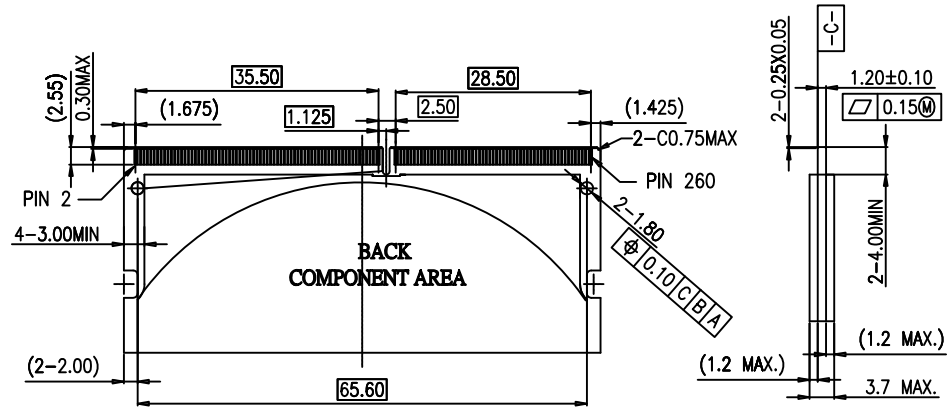
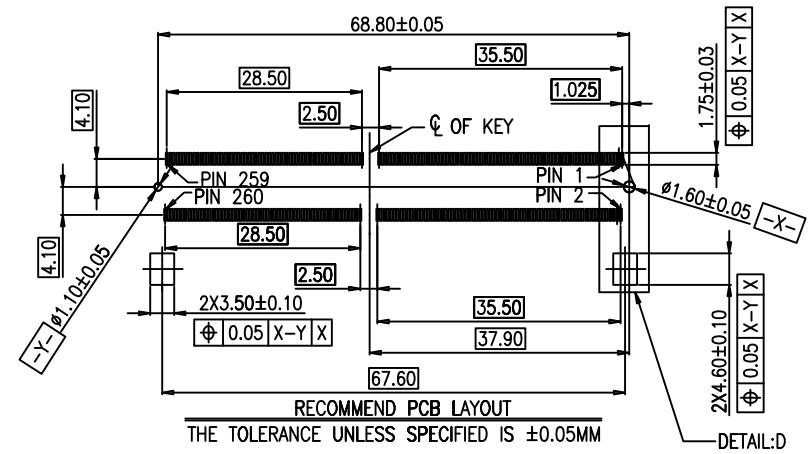
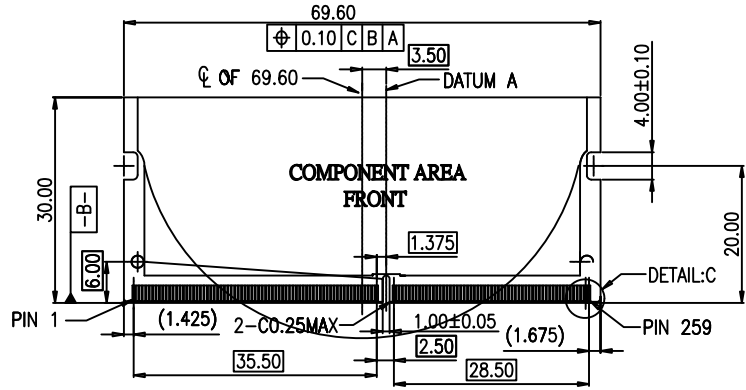
MATING: ① INSERTING(25°) → ② ROTATING → ③ FIXED  
 UNMATING: ④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING

NOTES:  
 1. MATERIAL:  
 1.1 HOUSING: LCP, UL 94V-0, COLOR: BLACK.  
 1.2 CONTACT: PHOSPHOR BRONZE.  
 1.3 SOLDER PEG AND LATCH: STAINLESS STEEL.  
 2. FINISH:  
 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER.  
 GOLD FALSH PLATING ON SOLDERTAIL.  
 GOLD PLATING (THICKNESS SEE TABLE) ON CONTACT AREA.  
 2.2 SOLDER PEG:  
 50u" MIN NICKEL UNDERPLATED ALL OVER.  
 AU 2u" MAX ON SOLDERTAIL.



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司
X ± 0.50	X° ± 5°	
.X ± 0.30	.X° ± 2°	
.XX ± 0.20	.XX° ± 1°	名稱(TITLE) DDR4 SO DIMM 260PIN 正向 H:5.2mm
單位(UNIT) mm	料號(PART NO.) 7DDR4-F0-0007	圖號(DWG NO.) 7DDR4-F0-0007
審核(APPROVAL)	核對(CHECKED)	製圖(DRAWN)
比例 SCALE 1:1	張數 SHEET 1/3	更改 REV B

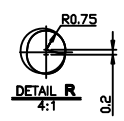
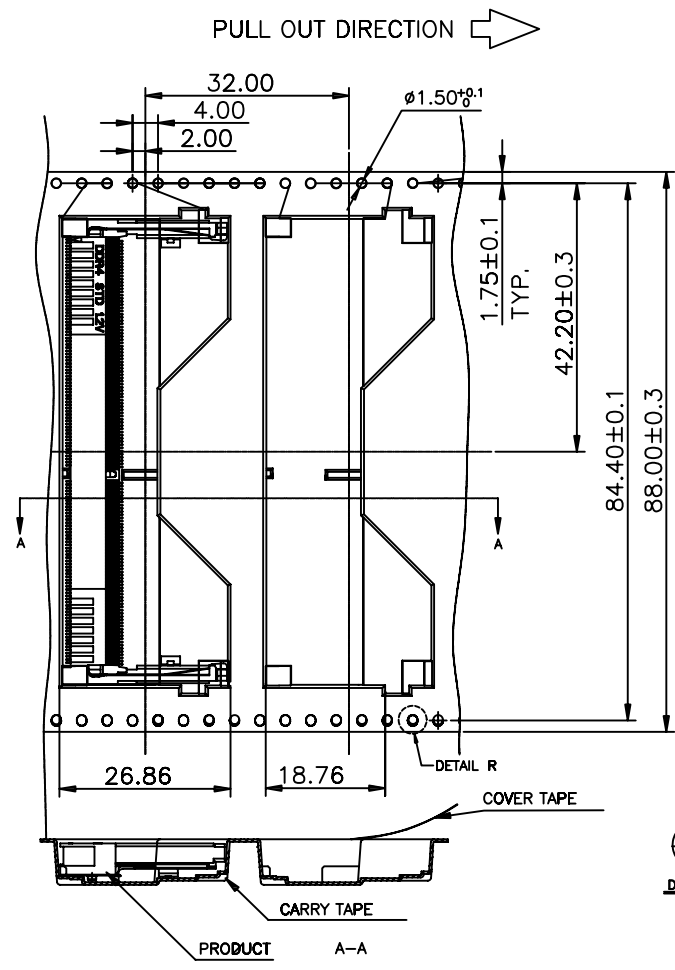
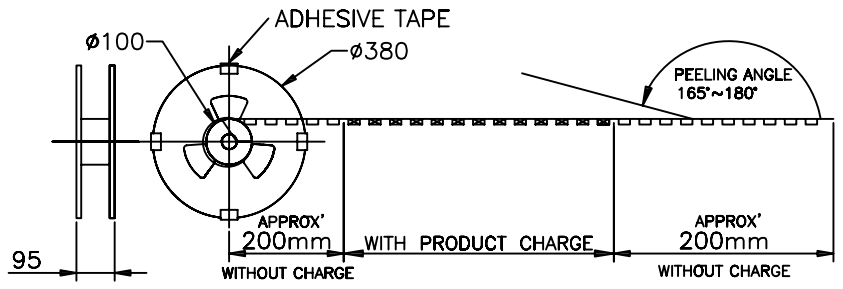
更改 REV	设计序号 MODIFICATION
A	EC06685
B	EC06954



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X°± 5°	名称/TITLE DDR4 SD DIMM 260PIN 正向 H:5.2mm	
.X± 0.30	.X°± 2°		
.XX± 0.20	.XX°± 1°		
单位/UNIT mm	料号/PART NO. 7DDR4-F0-0007	图号/DWG NO. 7DDR4-F0-0007	
审核/APPROVAL	核数/CHECKED	製圖/DRAWN	比例/SCALE 1:1
			张数/SHEET 2/3
			更改/REV B



更改 REV	變更內容 MODIFICATION
A	EC06685
B	EC06954



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司
X ± 0.50	X* ± 5°	
.X ± 0.30	.X* ± 2°	
.XX ± 0.20	.XX* ± 1°	名稱(TITLE) DDR4 SO DIMM 260PIN 正向 H:5.2mm
單位(UNIT) mm	料號(PART NO.) 7DDR4-F0-0007	圖號(DWG NO.) 7DDR4-F0-0007
審核(APPROVAL)	核對(CHECKED)	製圖(DRAWN)
		比例(SCALE) 1:1
		張數(SHEET) 3/3
		更改(REV) B